

Amendment under 37 C.F.R. §1.111
Attorney Docket No. 030984
Serial No.10/645,594

Amendments to the Specification:

Please replace the paragraph beginning at line 8 of page 4 of the current specification with the following amended paragraph:

~~As will be defined in claim 1, A~~ method of forming a protection film for covering an electronic component according to the present invention in order to achieve the aim set forth above is a method of forming at least two layers of protection films for covering an electronic component mounted on a surface of a substrate, the method comprising: a film forming step where a mask having an opening corresponding to the electronic component mounted on the surface of the substrate is disposed apart from the substrate by a predetermined first distance, and a film forming material is deposited through the opening of the mask onto the substrate and the electronic component as a first layer of protection film; and a film forming step where the mask is disposed apart from the substrate by a second distance longer than the first distance, and a film forming material is deposited through the opening of the mask onto the substrate and the electronic component as a second layer of protection film, wherein the steps are performed in turn, thereby at least forming the first layer of protection film for covering the electronic component and the second layer of protection film for covering beyond the first layer of protection film.

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Please replace the paragraph beginning at line 24 of page 4 of the current specification with the following amended paragraph:

~~As will be defined in claim 2~~ Moreover, a method of forming a protection film for covering an electronic device according to the present invention is a method of forming at least two layers of protection films for covering an electronic component mounted on a surface of a substrate, the method comprising: a film forming step where a mask having an opening corresponding to the electronic component mounted on the surface of the substrate is disposed between the substrate and a vapor source and a film forming material from the vapor source is deposited, through the opening of the mask apart from the substrate by a predetermined first distance, onto the substrate and the electronic component as a first layer of protection film; and a film forming step where the mask is disposed apart from the substrate by a second distance longer than the first distance, and a film forming material is deposited through the opening of the mask onto the substrate and the electronic component as a second layer of protection film, wherein the steps are performed in turn maintaining a distance between the substrate and the vapor source constant, thereby at least forming the first layer of protection film for covering the electronic component and the second layer of protection film for covering beyond the first layer of protection film.

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Please replace the paragraph beginning at line 12 of page 5 of the current specification with the following amended paragraph:

~~As will be defined in claim 4 Furthermore,~~ a method of forming a protection film for covering an electronic device according to the present invention is a method of forming at least two layers of protection films for covering an electronic component mounted on a surface of a substrate, the method comprising: a film forming step where a mask having an opening corresponding to the electronic component mounted on the surface of the substrate is disposed between the substrate and a vapor source, and a film forming material from the vapor source disposed apart from the substrate by a predetermined first distance is deposited through the opening of the mask onto the substrate and the electronic component as a first layer of protection film; and a film forming step where the vapor source is disposed apart from the substrate by a second distance shorter than the first distance, and a film forming material from the vapor source is deposited through the opening of the mask onto the substrate and the electronic component as a second layer of protection film, wherein the steps are performed in turn maintaining a distance between the substrate and the mask constant, thereby at least forming the first layer of protection film for covering the electronic component and the second layer of protection film for covering beyond the first layer of protection film.

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Please replace the paragraph beginning at line 28 of page 5 of the current specification with the following amended paragraph:

On the other hand, ~~as will be defined in claim 7~~, an electronic device having a protection film according to the present invention in order to achieve the aim set forth above is an electronic device having at least two layers of protection films so as to cover an electronic component mounted on a surface of a substrate, at least comprising: a first layer of protection film obtained by disposing a mask having an opening corresponding to the electronic component mounted on the surface of the substrate apart from the substrate by a predetermined first distance, and depositing a film forming material , through the opening of the mask, onto the substrate and the electronic component; and a second layer of protection film obtained by disposing the mask apart from the substrate by a second distance longer than the first distance, and depositing a film forming material, through the opening of the mask, onto the substrate and the electronic component, wherein the second layer of protection film is formed on the first layer of protection film so as to cover beyond the first layer of protection film.

Please replace the paragraph beginning at line 13 of page 6 of the current specification with the following amended paragraph:

~~As will be defined in claim 8~~ Moreover, an electronic device having a protection film according to the present invention is an electronic device having at least two layers of protection films so as to cover an electronic component mounted on a surface of a substrate, at least

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comprising: a first layer of protection film obtained by disposing a mask having an opening corresponding to the electronic component mounted on the surface of the substrate between the substrate and a vapor source and depositing a film forming material from the vapor source, through the opening of the mask apart from the substrate by a predetermined first distance, onto the substrate and the electronic component; and a second layer of protection film obtained by disposing the mask apart from the substrate by a second distance longer than the first distance, and depositing a film forming material from the vapor source, through the opening of the mask, onto the substrate and the electronic component, wherein the second layer of protection film is formed on the first layer of protect ion film so as to cover beyond the first layer of protection film.

Please replace the paragraph beginning at line 27 of page 6 of the current specification with the following amended paragraph:

~~As will be defined in claim 9~~ Furthermore, an electronic device having a protection film according to the present invention is an electronic device having at least two layers of protection films so as to cover an electronic component mounted on a surface of a substrate, at least comprising: a first layer of protection film obtained by disposing a mask having an opening corresponding to the electronic component mounted on the surface of the substrate between the substrate and a vapor source and depositing a film forming material from the vapor source, through the opening of the mask apart from the substrate by a predetermined first distance, onto the substrate and the electronic component; and a second layer of protection film obtained by disposing the vapor source apart from the substrate by a second distance shorter than the first

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distance, and depositing a film forming material from the vapor source, through the opening of the mask, onto the substrate and the electronic component, wherein the second layer of protection film is formed on the first layer of protection film so as to cover beyond the first layer of protection film.